

# PATENT ABSTRACTS OF JAPAN

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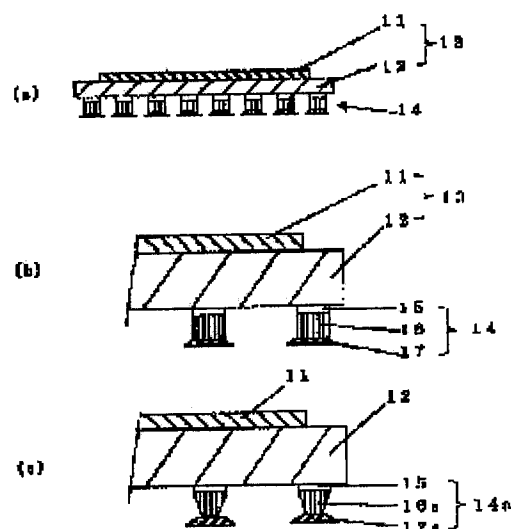
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## (54) ELECTRONIC PART, MANUFACTURE THEREOF, AND ELECTRONIC PART PACKAGE

### (57)Abstract:

**PROBLEM TO BE SOLVED:** To provide an electronic part excellent in connection reliability, its manufacturing method, and electronic part package by, when an electronic part is mounted on a wiring board by soldering, solving such problem that a crack occurs at a solder layer, etc., under the stress caused by difference in thermal expansion factor between an interposer substrate and wiring board for degraded connection reliability.

**SOLUTION:** A connection part 14 of an electronic part 13 where an LSI chip 11 is mounted on an interposer substrate 12 comprises an electrode 15, a stress relaxing structure 16, and a junction metal layer 17, with the cross-section of the junction metal layer 17 being trapezoid while the area of the surface contacting the stress relaxing structure 16 is smaller than that of opposite surface, so that, when the electric part 13 is mounted on a wiring board, a crack is prevented from occurring at a solder layer, etc., for improved connection reliability



of an electronic part package.